# PRODUCT/PROCESS CHANGE NOTICE (PCN)

<table>
<thead>
<tr>
<th>PCN Number:</th>
<th>21001A</th>
<th>Addendum</th>
</tr>
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<tbody>
<tr>
<td>Date Issued:</td>
<td>8/30/2021</td>
<td></td>
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<tr>
<td>Product(s) Affected:</td>
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<tr>
<th>SP322EBCA-L/TR</th>
<th>SP322EBEA-L/TR</th>
<th>SP322EBEY-L/TR</th>
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<td>SP322ECA-L/TR</td>
<td>SP322ECY-L/TR</td>
<td>SP322EEA-L/TR</td>
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<td>SP322EUEY-L/TR</td>
<td>SP323EBCA-L/TR</td>
<td>SP323EBCN-L</td>
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<td>SP323EBCY-L/TR</td>
<td>SP323EBEN-L/TR</td>
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<td>SP323EUCN-L</td>
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**Means of Distinguishing Changed Devices:**
- [ ] Product Mark:
- [ ] Back Mark
- [ ] Date Code
- [x] Other: Lot number

**Manufacturing Location Affected:** Refer to Description and Purpose of Change below

**Date Effective (90 day window):**
- August 13, 2021
- November 13, 2021

**Contact:**
Your local MaxLinear Marketing Representative or contact our Customer Support team by creating a Support Ticket at [http://www.maxlinear.com/support/createcase](http://www.maxlinear.com/support/createcase)

**Phone:** 1-760-692-0711

**Description and Purpose of Change:**
MaxLinear has qualified Key Foundry wafer foundry in order to increase production capacity and to facilitate long term support of the product line. The wafer process is 0.18um BCD. There is no change to form, fit, function and the products meet existing datasheet specifications.

In addition to the currently qualified ANST site, Greatek is added as an alternate site for package, assembly, and test.

There are no changes in device reliability.

Note: Users who rely on DC, diode characteristics during ICT testing should take caution certain I/O characteristics may appear changed due to the proprietary I/O structures employed by Key Foundry. These DC / diode characteristic differences are not guaranteed nor required to ensure full design functionality per datasheet. Adjustments at ICT testing may be required to prevent false failures.

**Addendum 08/26/2021:**
Remove EOL part → SP322EHEY-L, reference PDN 17-0626-02

**Samples:**
- [ ] Request from MaxLinear Marketing Representatives
- [x] No

**Attachment:**
- [ ] Yes
- [x] No

**Other:**
- Die Technology
- Wafer Fabrication
- Assembly Process
- Equipment
- Material
- Testing
- Product Design
- Manufacturing Site
- Data Sheet
- Yield Enhancement
- Software
- Other:

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Process Change Notification Form
Document Number BMS-02-0006Revision 6.0
Reliability/Qualification Summary: Reliability reports available upon request

Customer Acknowledgement of Receipt within 30 days of issue. Lack of acknowledgement within 30 days constitutes acceptance of change.

Please fax or email this form to the contact above after completing the following information:

Customer: ___________________________
Name: ______________________________________
Title: _______________________________________
Date: _______________________________________
E-Mail: _____________________________________
Phone: _____________________________________
Fax: _______________________________________

☐ Approval for shipments prior to effective date

Customer Comments (Optional):